

Substitute form 1449A/PTO

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Sheet 1 of 5 A4

Complete if Known

Application Number	10/601,938
Filing Date	June 23, 2003
First Named Inventor	Krishna K. Nair
Group Art Unit	2829
Examiner Name	Douglas M. Menz
Attorney Docket Number	9180-29

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		Number	Kind Code (if known)		
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Examiner Signature

Doug Menz

Date Considered

6/7/05

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Substitute form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)				Complete if Known		
				Application Number	10/601,938	
Sheet		2	of 5	A4	Examiner Name	Douglas M. Menz
					Attorney Docket Number	9180-29

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Examiner Signature		Date Considered	6/7/05
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				Group Art Unit	2829
				Examiner Name	Douglas M. Menz
(use as many sheets as necessary)				Attorney Docket Number	9180-29
Sheet	3	of 5	A4		

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			Group Art Unit	2829	
			Examiner Name	Douglas M. Menz	
Sheet	4	of 5	A4	Attorney Docket Number	9180-29

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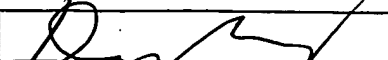
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<i>OP</i>	Electronics Packaging Conference, Austin, Texas, pp 14-25 (Sep. 29-Oct. 1, 1996).
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